

23. (new) A semiconductor device, comprising:

a leadframe, comprising:

a film of palladium on said leadframe;

a layer of palladium covering portions of said film of palladium.

24. (new) The semiconductor device of Claim 23, further comprising a layer of nickel on said leadframe onto which said film of palladium is deposited, wherein said film of palladium is sufficiently thin that the surface of said leadframe not covered by said layer of palladium comprises nickel and nickel oxide as well as palladium.

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#### REMARKS

Reconsideration of the above-referenced application in view of the amendments and the following remarks is respectfully requested.

Claims 1-16 were pending in this case. Claim 7 has been amended to more clearly define the features being claimed. Claims 17-20 are hereby cancelled in view of the election made by Applicants on 1/29/2002. New claims 21-24 have been added. Support for the newly added claims can be found, amongst other places within the specification, in the paragraph bridging pages 13 and 14.

Claim 7 stands rejected under 35 U.S.C. 112, second paragraph, as being indefinite. Applicant has amended Claim 7. The rejection is now moot.

Claims 1-3, 5, and 9 stand rejected under 35 U.S.C. 102(b) as being anticipated by Kim, et al. (U.S. Pat. No. 5,767,574. Applicants respectfully traverse the rejection.